## GaN HEMT 50V, 140W, 1.8-2.7GHz Power Transistor

### Description

The STAV27140C6 is a dual path 140W, internal matched GaN HEMT, operated from 1.8-2.7GHz. It features high gain, high efficiency, wide band and low cost, in 10\*6mm open cavity plastic package. It can be configured as a single stage asymmetrical Doherty capable of delivering Pavg of 20W. There is no guarantee of performance when this part is used outside of stated frequencies.

> Typical Doherty Single--Carrier W--CDMA Characterization Performance at 1.8GHz:

Input Signal :WCDMA 1 Carrier with PAR = 10 dB @ 0.01% Probability on CCDF , Pulsed CW: 20us, 10% VDD = 50 Vdc, IDQA = 60mA, VGSB = -5.5Vdc,

Freq	Ρι	ılse CW Signa	al	Pavg=43dBm WCDMA Signal			
(MHz)	P1-Gain	Psat	Psat	Cn (dP)	Eff (%)	ACPR5M (dBc)	
(10112)	(dB)	(dBm)	(dBm) (W) Gp (dB)	Gp (GB)	EII (70)		
1805	15.22	51.60	144.43	15.70	58.80	-29.85	
1842.5	15.28	51.62	145.23	15.66	59.42	-30.69	
1880	15.21	51.54	142.56	15.57	59.38	-32.59	

## Applications

- 5G Doherty amplifier within 2.5-2.7, 2.1-2.2, 1.8-1.9G either as driver or as final
- S band power amplifier
- L band power amplifier

### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

#### Turning the device ON

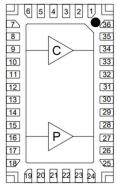
- 1. Set VGS to the pinch--off (VP) voltage, typically –5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

### Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

### Figure 1: Pin Connection definition

### Transparent top view (Backside grounding for source)



Pin No.	Symbol	Description				
9,10	RF IN/Vgs1	RF Input, Vgs bias for main path				



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15,16	RF IN/Vgs2	RF Input, Vgs bias for peak path
33,34	RF OUT/VDD1	RF Output, VDD bias for Main path
27,28	RF OUT/VDD2	RF Output, VDD bias for Peak path
Rest pins	NC	No connection
2,5,7,12,13,18,20,23,25,30,31,36,		DC/RF Ground. Must be soldered directly to heatsink or copper coin for
Package Base	GND	CW application.

#### **Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	+200	Vdc
GateSource Voltage	V <sub>GS</sub>	-8 to +0.5	Vdc
Operating Voltage	V <sub>DD</sub>	55	Vdc
Maximum gate current	lgs	17.5	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

#### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	RθJC	2.2	°C /W
$T_{\rm C}\text{=}85^{\circ}\text{C},$ Pdiss=15W at Pavg=43dBm WCDMA 1 carrier	KAIC	2.2	-0.700

Notes: Based on expected carrier amplifier efficiency of Doherty, Pavg assumes 10% peaking amplifier contribution of total average Doherty

rated power. Thermal resistance is measured to package backside

#### Table 3. Electrical Characteristics (TA = 25°C unless otherwise noted)

#### DC Characteristics (main path, measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=7.5mA	V <sub>DSS</sub>		200		V
Gate Threshold Voltage	VDS =10V, ID = 7.5mA	V <sub>GS(th)</sub>	-4		-2	V
Gate Quiescent Voltage	VDS =50V, IDS=60mA, Measured in Functional Test	V <sub>GS(Q)</sub>		-3.1		V

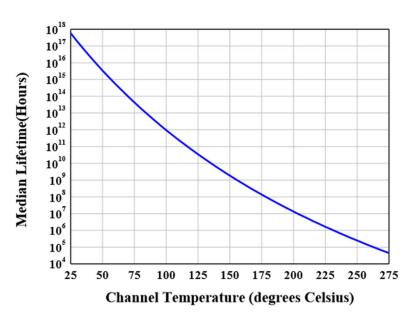
#### DC Characteristics (peak path, measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=10mA	V <sub>DSS</sub>		200		V
Gate Threshold Voltage	VDS =10V, ID = 10mA	V <sub>GS(th)</sub>	-4		-2	V
Gate Quiescent Voltage	VDS =50V, IDS=90mA, Measured in Functional Test	V <sub>GS(Q)</sub>		-3.1		V

#### **Ruggedness Characteristics**

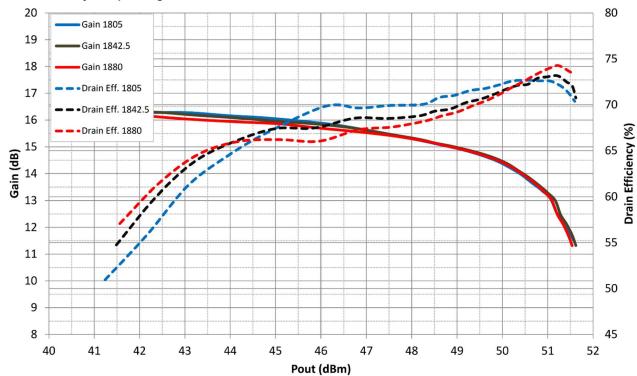
Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	2.6GHz, Pout=43dBm WCDMA					
	1 Carrier, All phase,	VSWR		10:1		
	No device damages					

Figure 2: Median Lifetime vs. Channel Temperature



Typical performance 1805-1880MHz Doherty

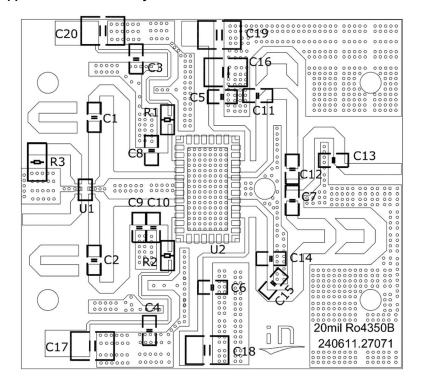
Figure 3: Efficiency and power gain as function of Pout



#### Figure 4: Network analyzer output, S11 and S21



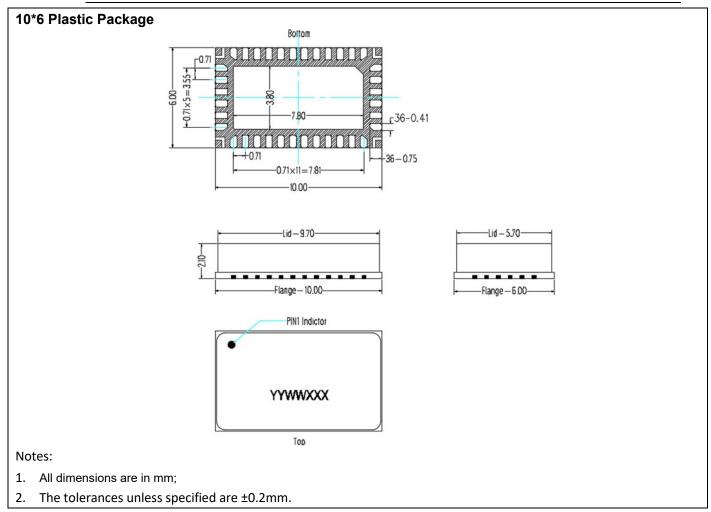
Figure 5: Picture of application board Doherty circuit



#### Table 4. Bill of materials of application board (PCB layout upon request, RO4350B 20mils)

Component	Value	Quantity
U1	C1720J5003AHF	1
U2	STAV27140C6	1
C1	8.2pF/250V	1
C8, C10	2.7pF/250V	2
C9	0.5pF/250V	1
C11, C15	2.0pF/250V	2
C14	0.9pF/250V	1
C12	4.3pF/250V	1
C13	1.3pF/250V	1
C2, C3, C4, C5, C6, C7	20pF/250V	6
C16, C17, C18, C19, C20	10 uF/100V	5
R3	<b>50</b> Ω	1
R1、R2	<b>10</b> Ω	2

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### **Revision history**

#### Table 4. Document revision history

Date	Revision	Datasheet Status
2024/6/27	V1.0	Preliminary Datasheet Creation

Application data based on: ZBB-24-17

#### Notice

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